# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model:**
[List multiple models if applicable.]

HP Spectre x360 15 Convertible PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP's Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</strong></td>
<td>With a surface greater than 10 sq cm M/B, micro sd Card D/B, Touch-Pad-PCB, Audio-D/B, IR board, touch board, Power D/B</td>
<td>7</td>
</tr>
<tr>
<td><strong>Batteries, excluding Li-Ion batteries.</strong></td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td><strong>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</strong></td>
<td>Battery(ies) are attached to the product by <em>(check all that apply with an “x” inside the “[]”):</em>[x] screws [ ] snaps [ ] adhesive [ ] other. Explain ______. NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>1</td>
</tr>
<tr>
<td><strong>Mercury-containing components</strong></td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td><strong>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</strong></td>
<td>Includes background illuminated displays with gas discharge lamps 15”6</td>
<td>1</td>
</tr>
<tr>
<td><strong>Cathode Ray Tubes (CRT)</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>Capacitors / condensers (Containing PCB/PCT)</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>External electrical cables and cords</strong></td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td><strong>Gas Discharge Lamps</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs</strong></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at [EL-MF877-01](#)
### Item Description | Notes | Quantity of items included in product
---|---|---
already listed as a separate item above) |  |
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. |  |
Components and waste containing asbestos |  |
Components, parts and materials containing refractory ceramic fibers |  |
Components, parts and materials containing radioactive substances |  |

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

#### Tool Description | Tool Size (if applicable)
---|---
Screw driver | #0,#1

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove base screw *2, base rubber foot, screw *8 and base sub-assy
2. Remove battery screw *6, release battery connector and remove battery
3. Remove Mylar, L/R fan housing screw *4, thermal pipe screw *6, SSD Card screw *1
4. Take out L/R fan and thermal pipe, SSD, shielding can, Ram module
5. Remove L/R speaker screw *8, Micro SD card board screw *2, TP screw *3, M/B screw *5, fingerprint *1, IR screw*1, power board screw*1
6. Release fingerprint connector, fingerprint hold bkt, TP connector, KB connector, KB light connector, IR board connector
7. Remove L/R speaker, TP, MB, SD card board and FFC *3 (Toughpad, SD card FFC, Power FFC)
8. Take out speaker, Micro SD board, TP module, fingerprint module, IR Board, power board, DC cable, M/B board
9. Remove Hinge screw *4 and LCD module assy

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part
3.22 Remove Rear side rubber, base screw and base assy

3.23 Remove Mylar, SSD card, Thermal pipe and fan, ram and shielding can, battery, all screw.

3.24 Remove Touchpad module, MB board, speaker, IR board, Micro SD Board, Power board, Micro SD FFC, Audio FFC, IR FFC, Power FFC, Touchpad FFC and all screw.
3.25 The LCD module is not disassembly